

# TLP759(IGM)

Transistor Inverters  
 Air Conditioners  
 Line Receiver  
 Intelligent Power Modules (IPMs) Interfaces

The TOSHIBA TLP759(IGM) consists of a high-output infrared emitting diode optically coupled to a high-speed photodiode with a transistor amplifier and is housed in an 8-pin DIP.

The TLP759(IGM) has no internal base connection. The Faraday shield in the photodetector chip provides an effective common-mode noise transient immunity.

The TLP759(IGM) guarantees minimum and maximum propagation delay, relative time difference between the rise and fall time, and common-mode transient immunity. Therefore, the TLP759(IGM) is suitable for an isolation interface between an intelligent power module (IPM) and a control IC in motor control applications.

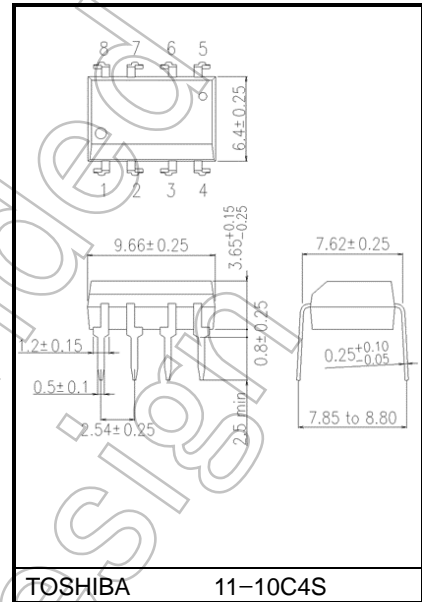
- Isolation voltage: 5000V<sub>rms</sub> (min)
- Common-mode transient immunity: ±10 kV / μs (min)  
 @V<sub>CM</sub> = 1500 V<sub>p-p</sub>
- Switching Time: t<sub>pHL</sub>, t<sub>pLH</sub> = 0.1 μs (min), = 0.8 μs (max)  
 @I<sub>F</sub> = 10 mA, V<sub>CC</sub> = 15 V, R<sub>L</sub> = 20 kΩ, T<sub>a</sub> = 25°C
- Switching time dispersion: 0.7 μs (max)  
 (|t<sub>pLH</sub> - t<sub>pHL</sub>|)
- TTL compatible
- UL-recognized: UL 1577, File No.E67349
- cUL-recognized: CSA Component Acceptance Service No.5A  
 File No.E67349
- VDE-approved: EN 60747-5-5 (Note 1)

Note 1 : When a VDE-approved type is needed, please designate the **Option (D4)**.

**Construction mechanical rating**

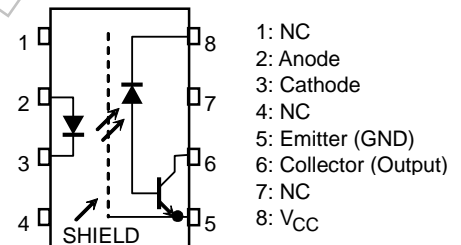
	7.62-mm pitch standard type	10.16-mm pitch TLP759F(IGM) type
Creepage Distance	7.0 mm (min)	8.0 mm (min)
Clearance	7.0 mm (min)	8.0 mm (min)
Insulation Thickness	0.4 mm (min)	0.4 mm (min)

Unit: mm

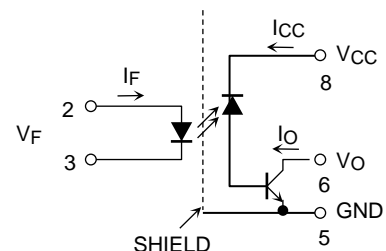


Weight: 0.54 g (typ.)

**Pin Configuration (top view)**



**Schematic**



Start of commercial production  
 1995-01

### Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
LED	Forward current (Note 1)	I <sub>F</sub>	25	mA
	Pulse forward current (Note 2)	I <sub>FP</sub>	50	mA
	Peak transient forward current (Note 3)	I <sub>FPT</sub>	1	A
	Reverse voltage	V <sub>R</sub>	5	V
	Diode power dissipation (Note 4)	P <sub>D</sub>	45	mW
Detector	Output current	I <sub>O</sub>	8	mA
	Peak output current	I <sub>OP</sub>	16	mA
	Output voltage	V <sub>O</sub>	-0.5 to 20	V
	supply voltage	V <sub>CC</sub>	-0.5 to 30	V
	Output power dissipation (Note 5)	P <sub>O</sub>	100	mW
Operating temperature range		T <sub>opr</sub>	-55 to 100	°C
Storage temperature range		T <sub>stg</sub>	-55 to 125	°C
Lead solder temperature(10 s) (Note 6)		T <sub>sol</sub>	260	°C
Isolation voltage(AC, 60 s, R.H. ≤ 60 %)		BV <sub>S</sub>	5000	V <sub>rms</sub>

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 1): Derate 0.8 mA / °C above 70 °C.

(Note 2): 50 % duty cycle, 1 ms pulse width.

Derate 1.6 mA / °C above 70 °C.

(Note 3): Pulse width PW ≤ 1 μs, 300 pps.

(Note 4): Derate 0.9 mW / °C above 70 °C.

(Note 5): Derate 2 mW / °C above 70 °C.

(Note 6): Soldering portion of lead: Up to 2 mm from the body of the device

(Note 7): Device considers a two-terminal device: Pins 1, 2, 3 and 4 shorted together and pins 5, 6, 7 and 8 shorted together.

### Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
LED	Forward voltage	$V_F$	$I_F = 16 \text{ mA}$		1.65	1.85	V
	Forward voltage temperature coefficient	$\Delta V_F / \Delta T_a$	$I_F = 16 \text{ mA}$	—	-2	—	mV / °C
	Reverse current	$I_R$	$V_R = 5 \text{ V}$	—	—	10	$\mu\text{A}$
	Capacitance between terminal	$C_T$	$V_F = 0 \text{ V}, f = 1 \text{ MHz}$	—	100	—	pF
Detector	High level output current	$I_{OH(1)}$	$I_F = 0 \text{ mA}, V_{CC} = V_O = 5.5 \text{ V}$	—	3	500	nA
		$I_{OH(2)}$	$I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}, V_O = 20 \text{ V}$	—	—	5	$\mu\text{A}$
		$I_{OH}$	$I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}, V_O = 20 \text{ V}, T_a = 70 \text{ }^\circ\text{C}$	—	—	50	
	High level supply current	$I_{CCH}$	$I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}$	—	0.01	1	$\mu\text{A}$
	Supply voltage	$V_{CC}$	$I_{CC} = 0.01 \text{ mA}$	30	—	—	V
	Output voltage	$V_O$	$I_O = 0.5 \text{ mA}$	20	—	—	V

### Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Current transfer ratio	$I_O / I_F$	$I_F = 10 \text{ mA}, V_{CC} = 4.5 \text{ V}, V_O = 0.4 \text{ V}$	25	35	75	%
		$I_F = 10 \text{ mA}, V_{CC} = 4.5 \text{ V}, V_O = 0.4 \text{ V}, T_a = -25 \text{ to } 100 \text{ }^\circ\text{C}$	15	—	—	
Low level output voltage	$V_{OL}$	$I_F = 16 \text{ mA}, V_{CC} = 4.5 \text{ V}, I_O = 2.4 \text{ mA}$	—	—	0.4	V

### Isolation Characteristics (Ta = 25°C)

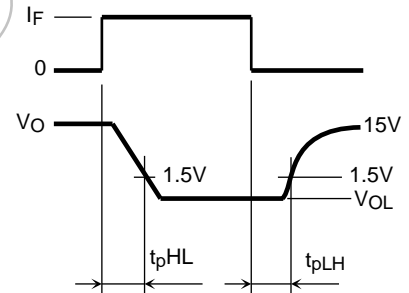
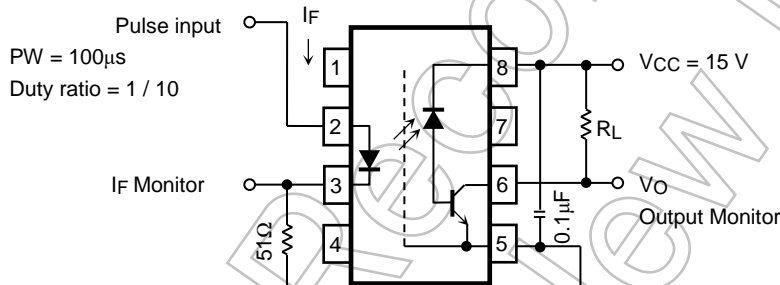
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Capacitance input to output	$C_S$	$V = 0 \text{ V}, f = 1 \text{ MHz}$ (Note 7)	—	0.8	—	pF
Isolation resistance	$R_S$	R.H. $\leq 60 \%$ , $V_S = 500 \text{ V}$ (Note 7)	$1 \times 10^{12}$	$10^{14}$	—	$\Omega$
Isolation voltage	$BVS$	AC, 60 s	5000	—	—	$V_{rms}$

### Switching Characteristics (Ta = 25°C, Vcc = 15V)

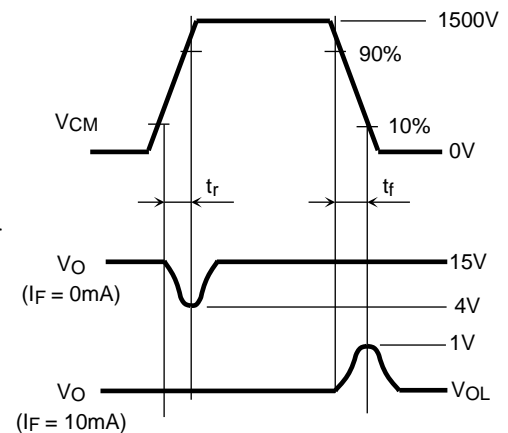
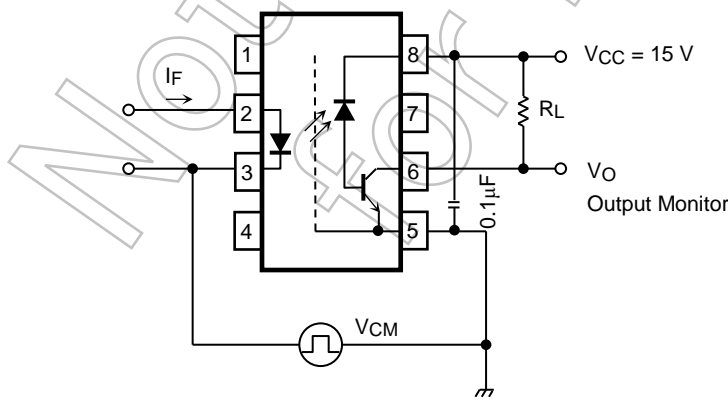
Characteristic	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Propagation delay time (H→L)	$t_{pHL}$	1	$I_F = 10 \text{ mA}, R_L = 20 \text{ k}\Omega$	0.1	0.45	0.8	$\mu\text{s}$
			$I_F = 10 \text{ mA}, R_L = 20 \text{ k}\Omega$ $T_a = 0 \text{ to } 85 \text{ }^\circ\text{C}$	0.1	0.45	0.9	
Propagation delay time (L→H)	$t_{pLH}$		$I_F = 10 \text{ mA}, R_L = 20 \text{ k}\Omega$ $T_a = -25 \text{ to } 100 \text{ }^\circ\text{C}$	0.1	0.45	1.0	$\mu\text{s}$
			$I_F = 10 \text{ mA}, R_L = 20 \text{ k}\Omega$	—	0.15	0.7	
Switching time dispersion between on and off	$ t_{pLH} - t_{pHL} $		$I_F = 10 \text{ mA}, R_L = 20 \text{ k}\Omega$ $T_a = 0 \text{ to } 85 \text{ }^\circ\text{C}$	—	0.25	0.8	$\mu\text{s}$
			$I_F = 10 \text{ mA}, R_L = 20 \text{ k}\Omega$ $T_a = -25 \text{ to } 100 \text{ }^\circ\text{C}$	—	0.25	0.9	
Common mode transient immunity at logic high output (Note 8)	$CM_H$	2	$I_F = 0 \text{ mA}$ $V_{CM} = 1500 \text{ V}_{p-p}$ $R_L = 20 \text{ k}\Omega$	10000	15000	—	$\text{V} / \mu\text{s}$
Common mode transient immunity at logic low output (Note 8)	$CM_L$		$I_F = 10 \text{ mA}$ $V_{CM} = 1500 \text{ V}_{p-p}$ $R_L = 20 \text{ k}\Omega$	-10000	-15000	—	$\text{V} / \mu\text{s}$

(Note 8):  $CM_L$  is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic low state ( $V_O < 1 \text{ V}$ ).  
 $CM_H$  is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic high state ( $V_O > 4 \text{ V}$ ).

### Test Circuit 1: Switching Time Test Circuit



### Test Circuit 2: Common Mode Noise Immunity Test Circuit



$$CM_H = \frac{1200(\text{V})}{t_r(\mu\text{s})}, CM_L = \frac{1200(\text{V})}{t_f(\mu\text{s})}$$

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